

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-218 (canceled)

219. (currently amended) A chip package comprising:

a substrate;

only one die having a [[first]]top surface at a first horizontal level higher than a second horizontal level of a top surface of said substrate, wherein said substrate has no portion at said first horizontal level:

an adhesive material joining said top surface of said substrate and a bottom surface of said only one die;

a first insulating layer over said first horizontal level, [[over]]said only one die ~~and, over~~ said substrate and across an edge of said only one die, wherein said first insulating layer comprises a first portion vertically over said only one die and a second portion ~~over said substrate but not vertically~~ over said only one die;

a patterned circuit layer over said first insulating layer, [[over]]said first horizontal level, [[over]]said only one die ~~and, over~~ said substrate and across said edge, wherein said patterned circuit layer is connected to said only one die through a first opening in said first insulating layer; an inductor over said first horizontal level and [[over]]said first insulating layer; and a second insulating layer on said inductor.

220. (previously presented) The chip package of claim 219, wherein said only one die comprises a first trace formed therein, and wherein said patterned circuit layer comprises a second trace having a thickness greater than that of said first trace.

221. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises a power bus.

222. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises a ground bus.

223. (previously presented) The chip package of claim 219, wherein said patterned circuit layer connects multiple portions of said only one die.

Claims 224-227 (canceled)

228. (previously presented) The chip package of claim 219, wherein said first insulating layer comprises polyimide.

Claims 229-231 (canceled)

232. (previously presented) The chip package of claim 219, wherein said first insulating layer comprises benzocyclobutene (BCB).

Claims 233-235 (canceled)

236. (currently amended) The chip package of claim 219, wherein said adhesive material comprises a conductive paste joining said top surface of said substrate and said bottom surface of said only one die.

Claim 237 (canceled)

238. (currently amended) The chip package of claim 219, wherein said adhesive material comprises an adhesive tape joining said top surface of said substrate and said bottom surface of said only one die.

239. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises an electroplated metal.

240. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises a sputtered metal.

241. (previously presented) The chip package of claim 219, wherein said inductor has a portion vertically over said substrate but not vertically over said only one die.

242. (previously presented) The chip package of claim 219 further comprising a metal bump having a portion vertically over said substrate but not vertically over said only one die.

Claims 243-249 (canceled)

250. (canceled)

251. (currently amended) The chip package of claim 219, wherein said second portion of said first insulating layer is vertically over said substrate. ~~substrate has a second top surface substantially coplanar with said first top surface.~~

Claims 252-256 (canceled)

257. (currently amended) The chip package of claim 219 further comprising a polymer layer on said substrate, wherein said only one die is a second opening in said polymer layer, ~~is over said substrate and accommodates said only one die.~~

Claim 258 (canceled)

259. (previously presented) The chip package of claim 257, wherein said polymer layer comprises epoxy.

260. (currently amended) The chip package of claim 219 further comprising a solder bump over said first horizontal level.

Claim 261 (canceled)

262. (currently amended) The chip package of claim 219 further comprising a gold bump over said first horizontal level.

263. (previously presented) The chip package of claim 219, wherein said only one die comprises multiple active devices, and said patterned circuit layer connects said multiple active devices.

264. (currently amended) The chip package of claim 219, wherein said substrate comprises a silicon substrate.

265. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises copper.

266. (currently amended) The chip package of claim 219, wherein said substrate comprises a metal layer.

267. (previously presented) The chip package of claim 219, wherein said inductor comprises copper.